



EV Group lithography solutions for heterogeneous integration and wafer-level packaging to be highlighted at ECTC 2022 – May 25, 2022



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May 25, 2022



## Top Stories

### [Gov. Whitmer announces new semiconductor career and apprenticeship network program aimed at creating good-paying jobs](#)

Today, Governor Gretchen Whitmer joined the Michigan Economic Development Corporation to announce Michigan Strategic Fund (MSF) approval of support for a new semiconductor technician apprenticeship program intended to strengthen the pipeline of the semiconductor workforce. [More>>](#)



## Tech News

### [Ayar Labs to accelerate development and application of optical interconnects in artificial intelligence machine learning architectures with NVIDIA](#)

Ayar Labs is developing with NVIDIA groundbreaking artificial intelligence (AI) infrastructure based on optical I/O technology to meet future demands of AI and high performance computing (HPC) workloads. [More>>](#)

### [EV Group lithography solutions for heterogeneous integration and wafer-level packaging to be highlighted at ECTC 2022](#)

EV Group (EVG) announced that new developments in heterogeneous integration and wafer-level packaging enabled by its advanced lithography solutions will be highlighted in several papers being presented at the 2022 IEEE 72nd Electronic Components and Technology Conference (ECTC), to be held May 31-June 3 in San Diego, Calif. [More>>](#)

## [FEATURED PRODUCT](#)

[Efficient Vacuum for Load Lock Chambers](#) – Busch TORRI BD multi-stage rotary lobe vacuum pumps are one of the smallest, lightest, and most

energy-efficient available. A tool interface works with machines to control and monitor the pump with logic such as contact closures and 24 VDC signals. Their best-in-class chamber pump-down time further reduces total average cycle times. [Learn more.](#)



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## Featured Video

EMD Electronics' Digital Solutions organization focuses on leveraging data in R&D, quality, and supply chain to solve industry challenges and accelerate learning cycles. Customers can proactively identify the parameters that matter for their fab performance before excursions occur. They can also gain better control of newly identified parameters to improve the performance of materials in their fabs, which can contribute to yield optimization. The learnings are also useful in R&D for new material innovation which accelerates the ramp up of next generation technology nodes. Watch this video interview with **Kutup Kurt, Head of Operations, Digital Solutions at EMD Electronics** to learn more.

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Kutup Kurt  
Head of Operations, Digital Solutions  
EMD Electronics

Pete Singer  
Editor-in-Chief  
Semiconductor Digest

Interview with Kutup Kurt, Head of Operations, Digital Solutions

## Business News

### [Samsung Electronics and Red Hat announce collaboration in the field of next-generation memory software](#)

Samsung Electronics Co., Ltd. and Red Hat, Inc. today announced a broad collaboration on software technologies for next-generation memory solutions. [More>>](#)

## Webinars and Technology Papers

**TSI — PID Tuning Liquid Flow Controllers for Fast Response & Stabilization Time for Microelectronic Process Applications Like CVD and ALD with Exceptional Accuracy and Repeatability**

[View Paper](#)

**When OES is in the Dark: New Metrology Solutions**

**for Advanced ALD, Chamber Management and Sub FAB  
Safety and Sustainability Applications**

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**Semiconductor Manufacturing and the Future**

[View on Demand](#)

**Panel Discussion on Automotive Electronics Reliability**

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**The Impact of TOC & Resistivity in Semiconductor UPW Systems**

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Reliability, Automotive Grade Materials Essential for Unfailing  
Performance**

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Technologies Entering the Automotive Domain**

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Valves and Pneumatic Control Systems**

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